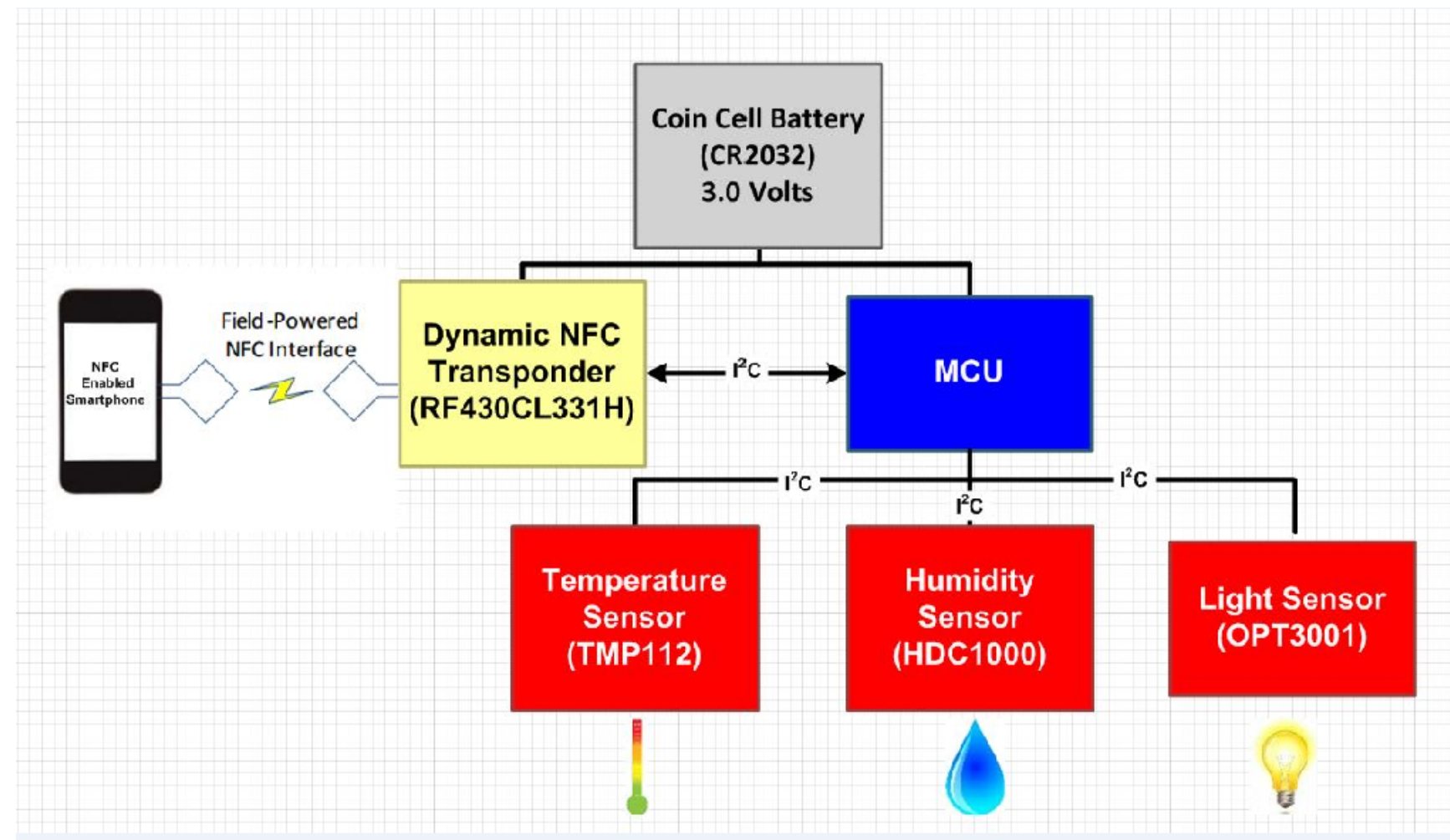


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

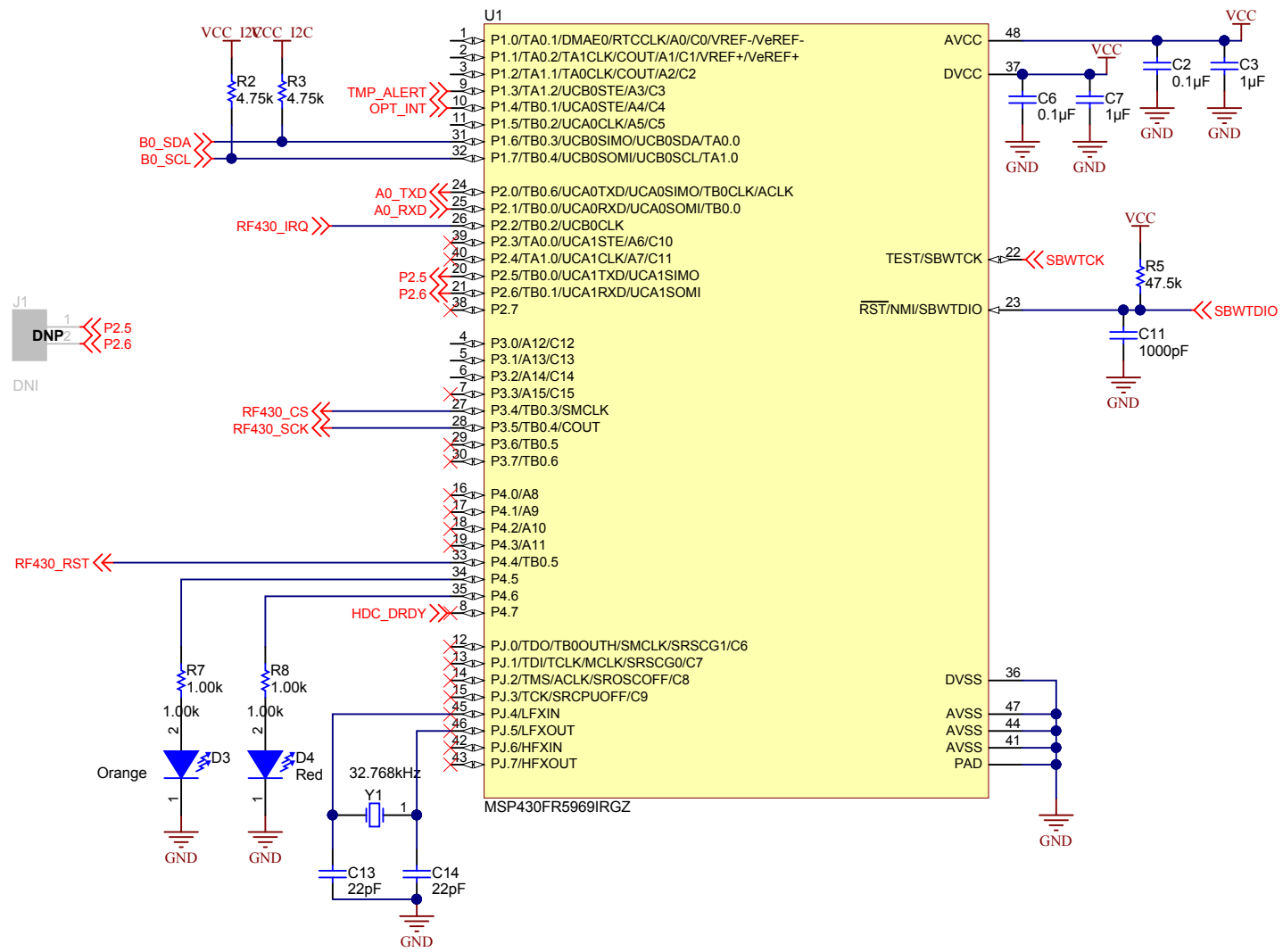


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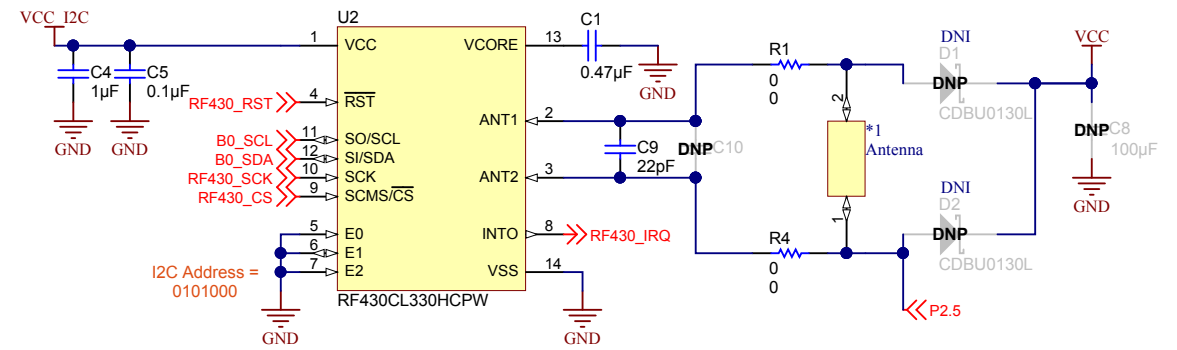
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TID #: TIDA-00524	Project Title: NFC-DATALOGGER-EVM	
Number: TIDA-00524	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3
Drawn By: Eddie LaCost	File: TIDA_00524_CoverSheet_SchDoc	Size: B
Engineer: Eddie LaCost	Contact: http://www.ti.com/support	http://www.ti.com

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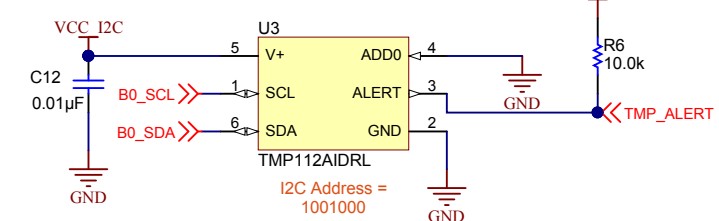
MSP430 Microcontroller



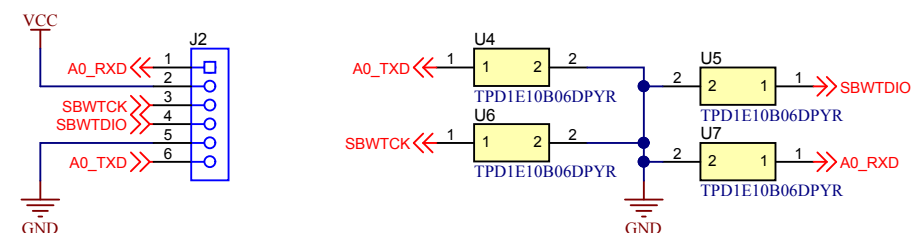
RF430 Dynamic NFC Transponder



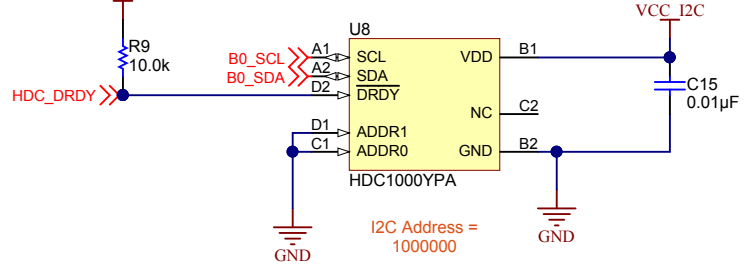
Local Temperature Sensor



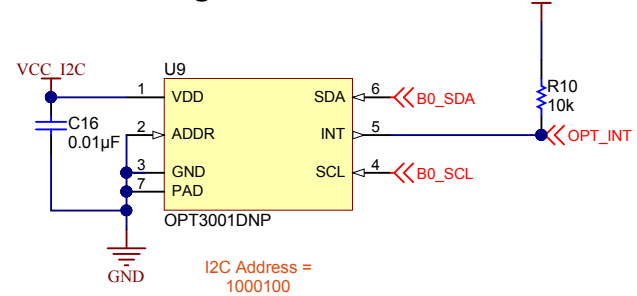
SBW Interface & ESD Protection



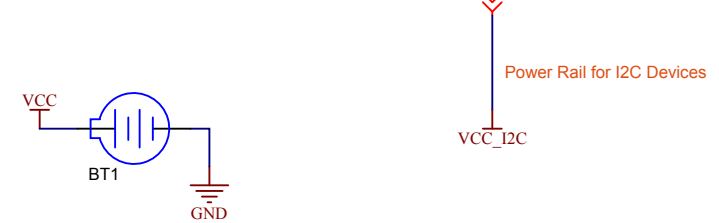
Local Humidity/Temperature Sensor



Light Sensor



CR2032 Battery Holder



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SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
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Engineer: Eddie LaCost	Contact: http://www.ti.com/support	



DNP FID1 DNP FID2 DNP FID3

PCB Number: TIDA-00524
PCB Rev: A

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Pb-Free Symbol

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FCC disclaimer

ZZ1
Assembly Note
This Assembly Note will show in the PcbDoc and associated outputs

ZZ2
Assembly Note
This Assembly Note will show in the PcbDoc and associated outputs

ZZ3
Assembly Note
This Assembly Note will show in the PcbDoc and associated outputs

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Number: TIDA-00524	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3
Drawn By:	File: TIDA00524_Hardware.SchDoc	Size: B
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